

Brandon Hamilton is joining the BAE Electronics Systems, Navigation & Sensor Systems as a Microelectronics Packaging Program Manager with over 20 years' experience in executing microelectronics advanced packaging programs. Brandon resides near NSWC Crane, the hub for many DoD microelectronics investments. Brandon holds 21 U.S. Patents/Patents pending and is an active member in IMAPS and multiple advanced packaging industry consortiums and working groups. He received his BS in Business Management from Houghton College.